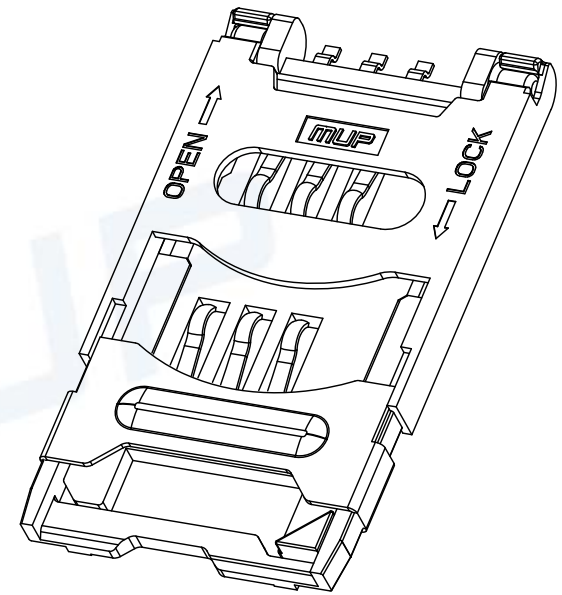
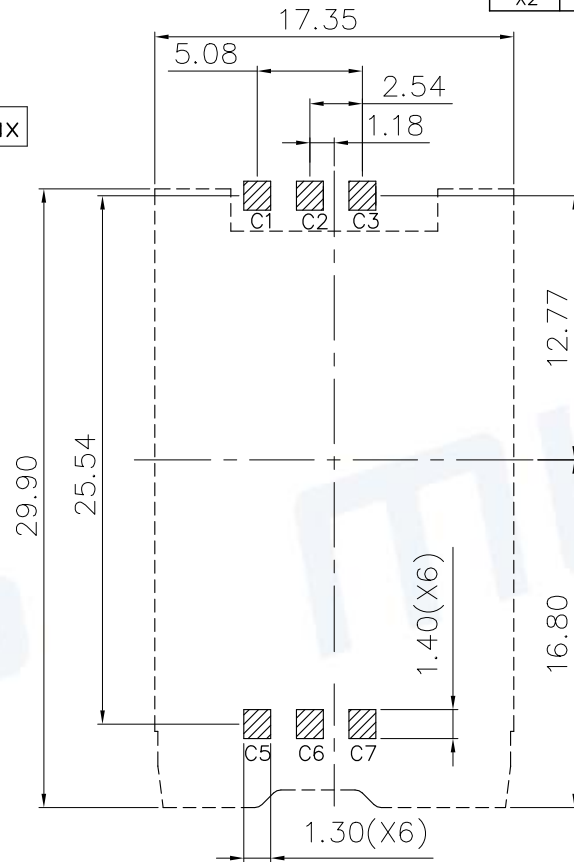
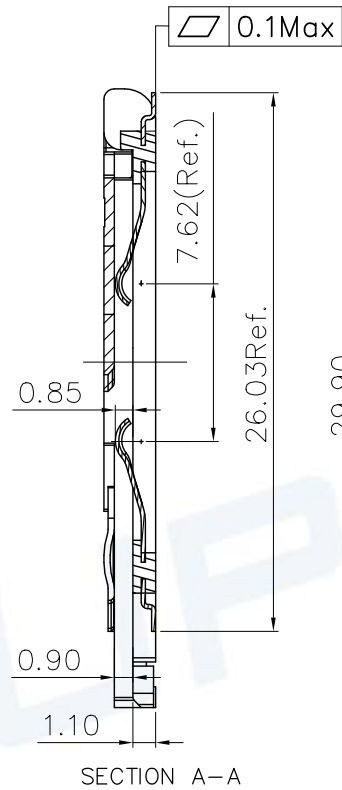
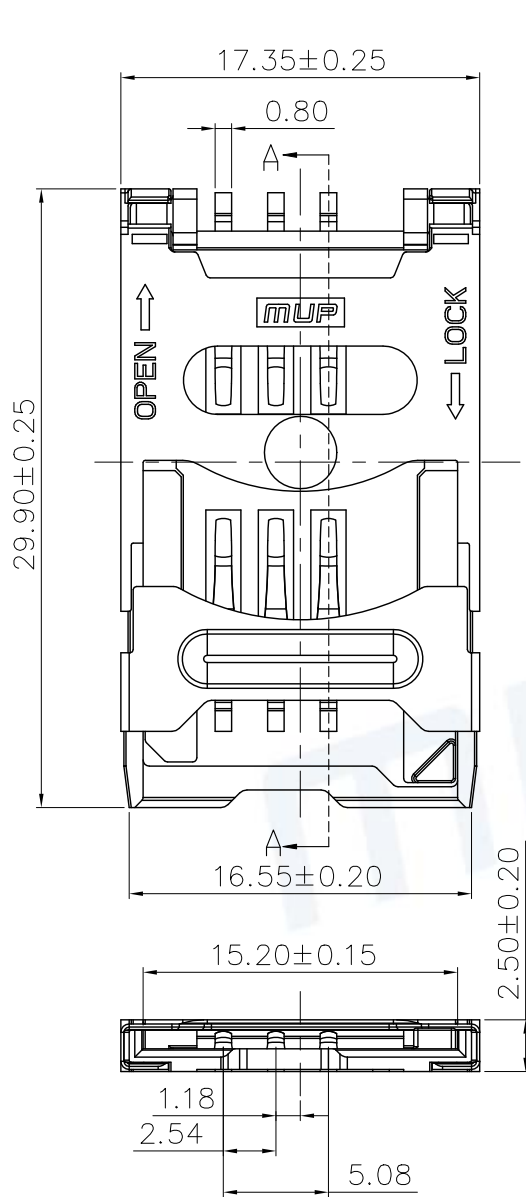


REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 29.90LX17.35WX2.50H mm
Weight: Approx1.20±0.2g
Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical,100mΩ max
Insulation resistance:>1000MΩ/500V DC

3.Solderability

Vapor phase: 215°C,30sec.Max
IR reflow: 250°C,5sec.Max
Manual soldering: 370°C,3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	BASE	1	Hi-temp Thermoplastic	Black UL94V-0
2	COVER	1	Hi-temp Thermoplastic	Black UL94V-0
3	DATA CONTACT	6	Copper Alloy	Contact area:Gold plated
4	SLIDER LOCKED	1	Stainless Steel	

Unless otherwise specified, other tolerance are:

X	±0.35	X*	±5*
X.X	±0.25	X.X*	±4*
X.XX	±0.15	X.XX*	±3*
X.XXX	±0.10	X.XXX*	±2*

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**
MODEL NO: **MUP C705-1**
TYPE: **H2.5 without post 6P**

PROJ.	UNIT	SCALE
①	mm	1:1

DRAWN	Zoey Jun.17.2008	DWG NO.:	MUP-C705-001
CHECKED	Jimmy Jun.17.2008	SHEET	1/1
APPROVAL	Simon Jun.17.2008	REVISION	X1



CUSTOMER DRAWING